

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	40	430/311,313,322,323.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:36
L6	454	"430"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:37
L7	183	"430"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:42
L8	182	"438"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:52
L9	310	"257"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:12
L10	141	"29"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:18
L11	68	"361"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:20
L12	3	(wafer board interposer carrier substrate) same saffire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:20
L13	24522	(wafer board interposer carrier substrate) same sapphire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:20

EAST Search History

L14	271	(wafer board interposer carrier substrate) same sapphire same grind\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 16:21
-----	-----	--	---	----	----	------------------

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	((("6593170") or ("6465158"))).PN.	USPAT	OR	OFF	2006/02/19 15:30
L4	40	430/311,313,322,323.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:36
L6	454	"430"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:37
L7	183	"430"/\$.ccls. and (wafer board interposer carrier substrate) and sand with blast\$3 and (grind\$4 lapp\$4 polish\$4 scribe\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/19 15:37